

# GP2S09/GP2S10/GP2S24/ GP2S26/GP2S27

Subminiature  
**Photointerrupter**

## ■ Features

### 1. Compact and thin

GP2S09 : Compact DIP long lead type

GP2S10 : Short lead flat type

GP2S24 : Compact DIP type

GP2S26 : Flat lead type

GP2S27 : Mini-flat package type

### 2. optimum detection distance : 0.6 to 0.8mm

### 3. Visible light cut-off type

## ■ Outline Dimensions

(Unit : mm)

GP2S09	GP2S10	GP2S24
<p>*Tolerance : <math>\pm 0.15\text{mm}</math> *): Reference dimensions *The dimensions indicated by * refer to those measured from the lead base.</p>	<p>*Tolerance : <math>\pm 0.15\text{mm}</math> *): Reference dimensions</p>	<p>*Tolerance : <math>\pm 0.15\text{mm}</math> *): Reference dimensions *The dimensions indicated by * refer to those measured from the lead base.</p>
GP2S26	GP2S27	Internal connection diagram (Common to 5 models)
<p>*Tolerance : <math>\pm 0.15\text{mm}</math> *): Reference dimensions</p>	<p>*Tolerance : <math>\pm 0.15\text{mm}</math> *): Reference dimensions</p>	<p>① Anode ② Emitter ③ Collector ④ Cathode</p>

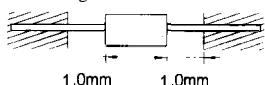
**Absolute Maximum Ratings**

(Ta = 25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	50	mA
	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	P	75	mW
output	Collector -emitter voltage	V <sub>CE0</sub>	35	V
	Emitter collector voltage	V <sub>EC0</sub>	6	V
	Collector current	I <sub>C</sub>	20	mA
	Collector power dissipation	P <sub>C</sub>	75	mW
	Total power dissipation	P <sub>tot</sub>	100	mW
	Operating temperature	T <sub>opr</sub>	-20 to +85	°C
	Storage temperature	T <sub>stg</sub>	-40 to +100	°C
*soldering temperature		T <sub>sol</sub>	260	°C

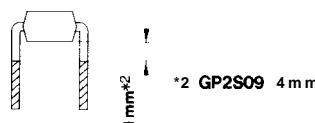
\*1 Within 5 seconds (Soldering areas for each model are shown below)

**GP2S10**  
Soldering area  
The hatched area more than 10mm away from the both edges of package as shown in the figure below.

**GP2S09, GP2S24**

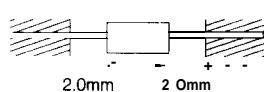
Soldering area

The hatched area more than 1mm\*2 away from the lower edge of package as shown in the figure below

**GP2S26**

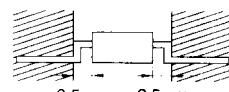
Soldering area

The hatched area more than 2.0mm away from the both edges of package as shown in the figure below.

**GP2S27**

Soldering area

The hatched area more than 0.5mm away from the both edges of package as shown in the figure below.

**Electro-optical Characteristics**

(Ta = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX	Unit
Input	Forward voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	—	1.2	1.4	V
	Reverse current	I <sub>R</sub>	V <sub>R</sub> =6V	—	10	10	μA
output	Collector dark current	I <sub>CEO</sub>	V <sub>CE</sub> =20V	—	10 <sup>-9</sup>	10 <sup>-7</sup>	A
	* <sup>3</sup> Collector current	I <sub>C</sub>	I <sub>F</sub> =4mA, V <sub>CE</sub> =2V	20	45	120	μA
Transfer characteristics	Rise time	t <sub>r</sub>	V <sub>CE</sub> =2V, I <sub>C</sub> =100 μA	—	20	100	μs
	Fall time	t <sub>f</sub>	R <sub>L</sub> =1k Ω, d=1mm	—	20	100	μs
* <sup>4</sup> Leak current		I <sub>LEAK</sub>	I <sub>F</sub> =4mA, V <sub>CE</sub> =2V	—	—	0.1	μA

\*3 The condition and arrangement of the reflective object are shown below

\*4 Without reflective object

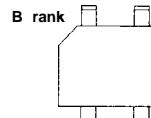
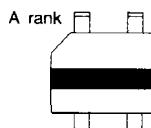
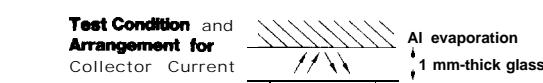
The ranking of collector current shall be classified into the following 6 ranks.

(GP2S09, GP2S10, GP2S24, GP2S26, GP2S27)

Rank	Collector current I <sub>C</sub> (Y A)
*A	20 to 42
B	34 to 71
C	58 to 120
A or B	20 to 71
B or C	34 to 120
A, B or C	20 to 120

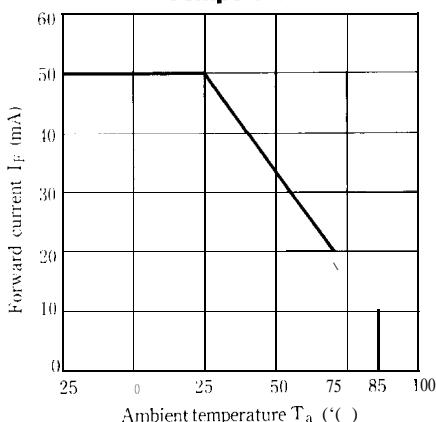
\*5 GP2S24 and GP2S26 don't have A rank

Test Condition and Arrangement for Collector Current

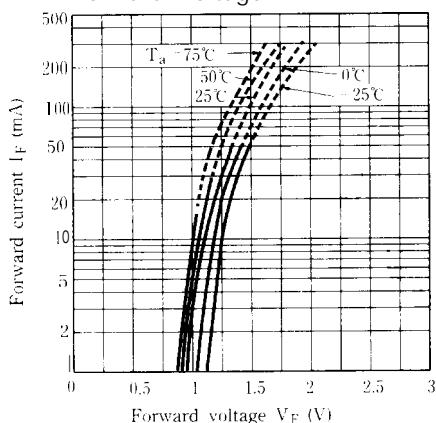


\*\* Marking is shown in the rear face of device

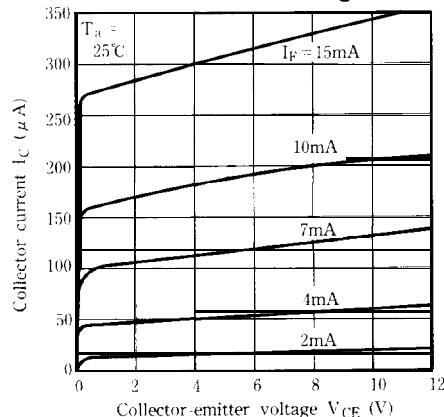
**Fig. 1 Forward Current vs. Ambient Temperature**



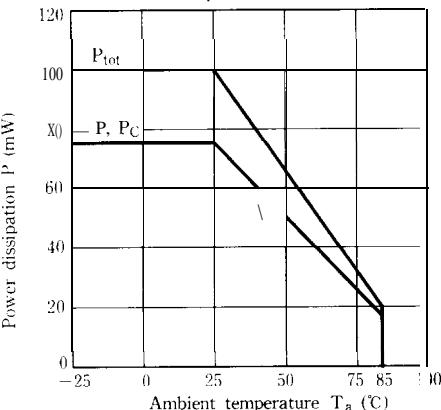
**Fig. 3 Forward Current vs. Forward Voltage**



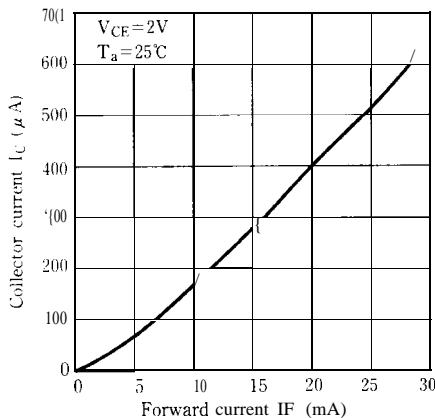
**Fig. 5 Collector Current vs. Collector-Emitter Voltage**



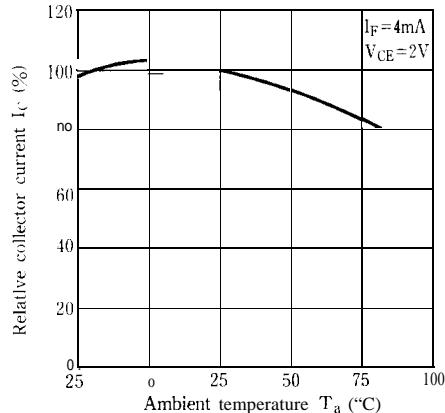
**Fig. 2 Power Dissipation vs. Ambient Temperature**



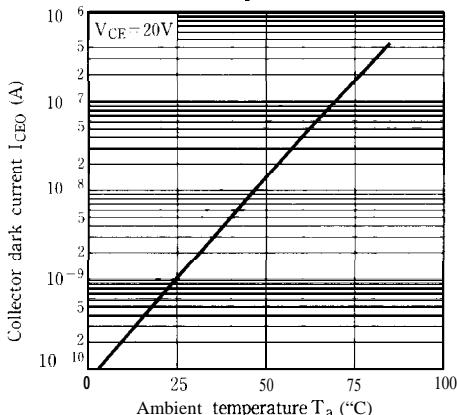
**Fig. 4 Collector Current vs. Forward Current**



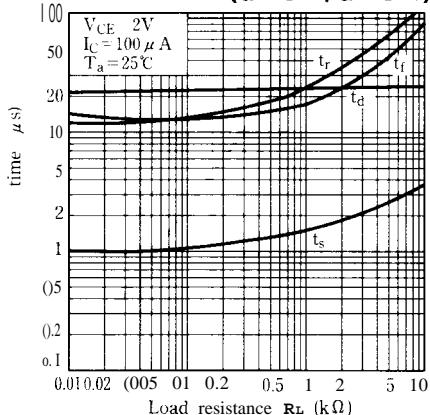
**Fig. 6 Relative Collector current vs. Ambient Temperature**



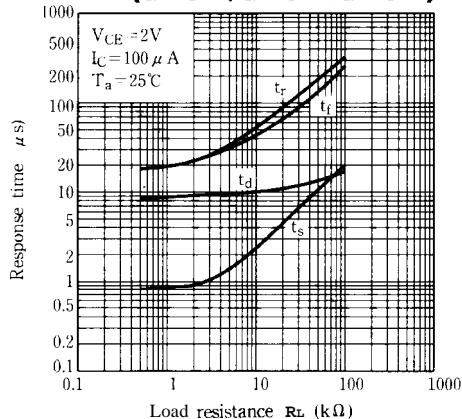
**Fig. 7 Collector Dark Current vs. Ambient Temperature**



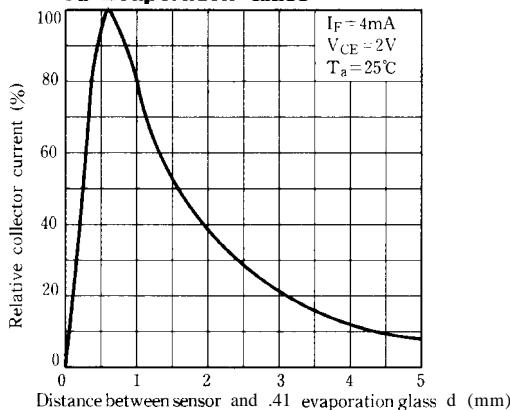
**Fig. 8 Response Time vs. Load Resistance (GP2S09/GP2S10)**



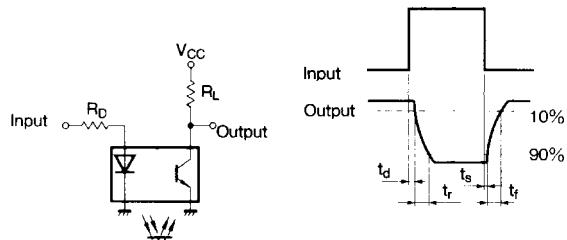
**Fig. 9 Response Time vs. Load Resistance (GP2S24/GP2S26/GP2S27)**



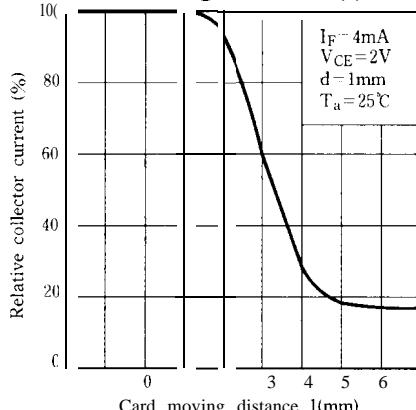
**Fig.10 Relative Collector Current vs. Distance between Sensor and Al Evaporation Glass**



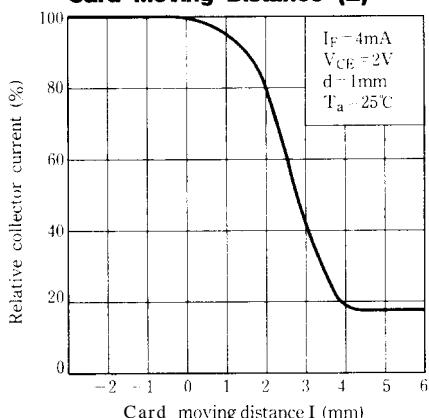
**Test Circuit for Response Time**



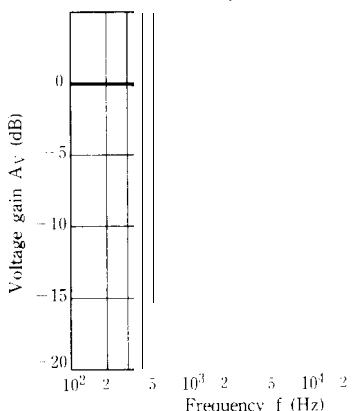
**Fig.11 Relative Collector Current vs. Card Moving Distance (1)**



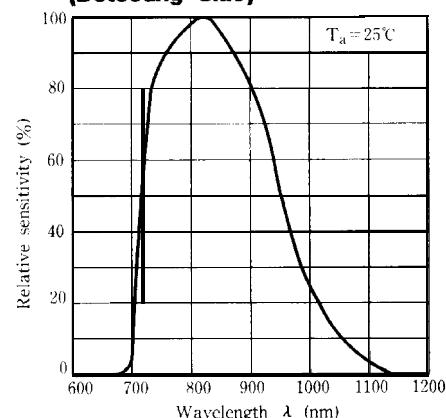
**Fig.12 Relative Collector Current vs. Card Moving Distance (2)**



**Fig.13-a Frequency Response**  
(GP2S09/GP2S10)

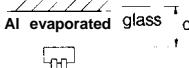


**Fig.14 Spectral Sensitivity  
(Detecting Side)**



**Test Condition for Distance & Detecting Position Characteristics (EX : GP2S24)**

Correspond to Fig.10



Correspond to Fig.11

Test condition

$I_F = 4\text{mA}$

$V_{CE} = 2\text{V}$

$d = 1\text{mm}$

OMS card

White      Black

$d$



$1\text{mm}$

Correspond to Fig.12

Test condition

$I_F = 4\text{mA}$

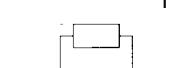
$V_{CE} = 2\text{V}$

$d = 1\text{mm}$

OMS card

White      Black

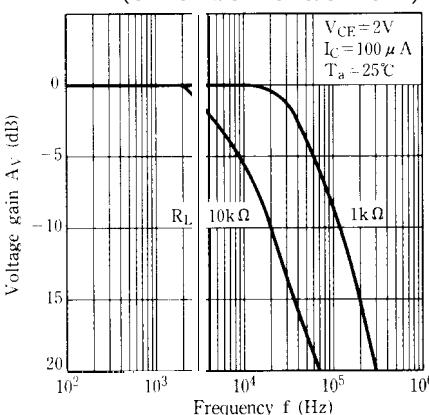
$d$



$1\text{mm}$

**Fig.13-b Frequency Response**

(GP2S24/GP2S26/GP2S27)



- Please refer to the chapter "Precautions for Use" (Page 78 to 93).